



**Please note that Cypress is an Infineon Technologies Company.**

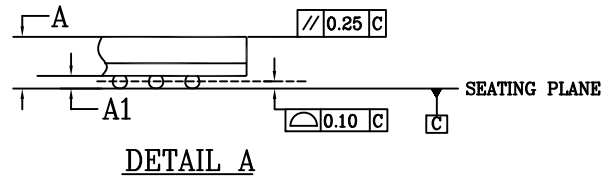
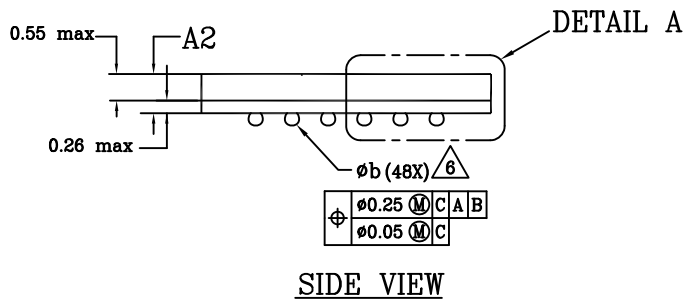
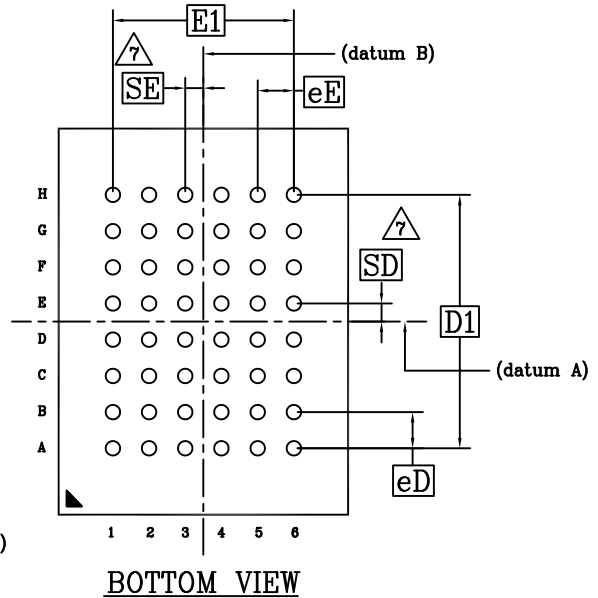
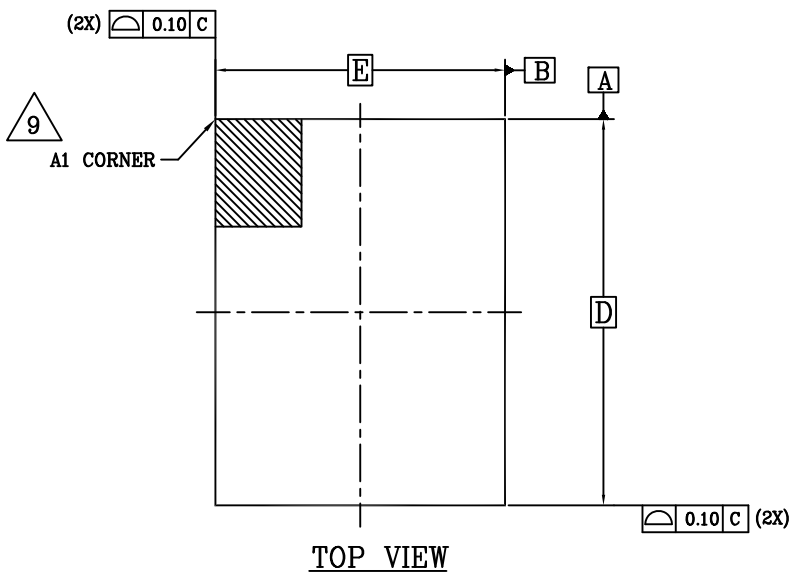
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.




SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.16	-	-
A2	-	-	0.81
D	8.00 BSC		
E	6.00 BSC		
D1	5.25 BSC		
E1	3.75 BSC		
MD	8		
ME	6		
n	48		
∅ b	0.25	0.30	0.35
eE	0.75 BSC		
eD	0.75 BSC		
SD	0.375 BSC		
SE	0.375 BSC		

**NOTES:**

- DIMENSIONING AND TOLERANCING METHODS PER ASME Y14.5M-2009.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
- [e] REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. n IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
6. DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
7. "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW "SD" OR "SE" = 0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" = eD/2 AND "SE" = eE/2.
- "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED BALLS.
9. A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK METALIZED MARK, INDENTATION OR OTHER MEANS.

REVISIONS			
Rev	ECN No.	Orig. of change	Reason for Revision
**	111203	-	CREATED DWG TEMPLATE
*A	118367	-	CHG. PKG. BODY TOLERANCE/ADD MOLD CAP & SUBSTRATE DIM./ CHG. LEAD COPLANARITY & BALL HEIGHT
*B	121987	-	CHG. MOLD CAP DIM. & SUBSTRATE DIM./ CHG. TITLE
*C	391420	-	CHG. COPLANARITY FROM 0.15 TO 0.10
*D	395148	-	CHG PKG CODE FROM BV48A TO BV
*E	2780421	-	CHANGE DRAWING FORMAT & CHANGE TITLE FROM 48 VFBGA 6X8X1.0 MM PACKAGE OUTLINE TO PACKAGE OUTLINE, 48L VFBGA 6X8X1.0 MM BV48/BZ48
*F	3013601	-	Change N.A. to Production on the Status Bar.
*G	3362447	-	Update for sunset review, no changed
*H	3740076	-	Added "Package Weight: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web".
*I	6307158	KOTA	Convert to new Cypress format. Add package code VCF048

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<b>TITLE</b> PACKAGE OUTLINE, 48 BALL VFBGA 6X8X1.0 MM BV48/BZ48VCF048	
<b>SPEC NO.</b> 51-85150	<b>REV</b> *I
<b>SCALE</b>	<b>SHEET</b> 2 OF 2

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PACKAGE  
CODE(S)

BV48  
BZ48  
VCF048

DRAWN BY

KOTA

DATE

12-SEP-18

APPROVED BY

UMPA

DATE

12-SEP-18